



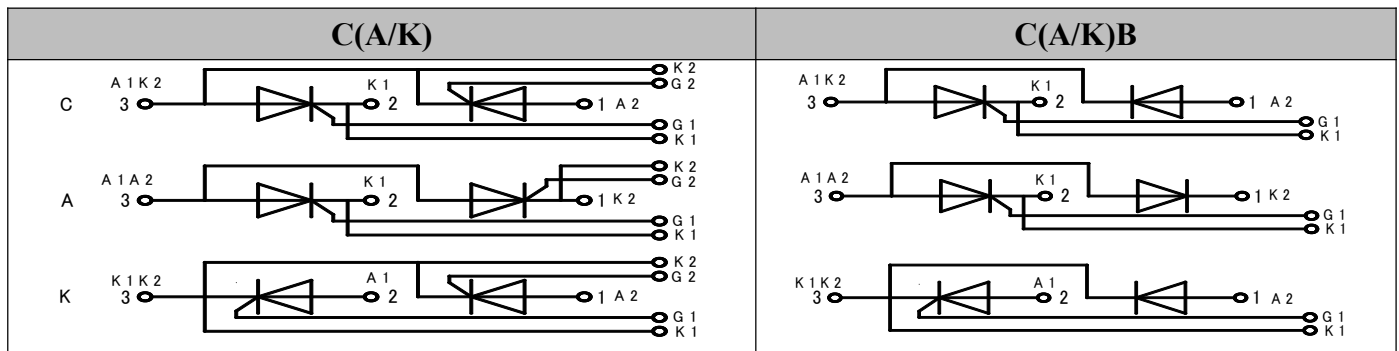
## Applications

- Power Converters
- Lighting Control
- DC Motor Control and Drives
- Heat and temperature control

## Features

- International standard package
- High Surge Capability
- Simple Mounting

## Internal Circuit



## Blocking - Off State

TYPE		VDRM/VRRM	VDSM/VRSM	Units
MT200C(A/K)28T3	MT200C(A/K)B28T3	2800	2900	V
MT200C(A/K)30T3	MT200C(A/K)B30T3	3000	3100	V
MT200C(A/K)32T3	MT200C(A/K)B32T3	3200	3300	V
MT200C(A/K)34T3	MT200C(A/K)B34T3	3400	3500	V
MT200C(A/K)36T3	MT200C(A/K)B36T3	3600	3700	V

## Maximum Ratings

Symbol	Conditions	Values	Units
$I_{TAV}$	Sine 180°; $T_c=85^\circ\text{C}$	200	A
$I_{TSM}$	$T_{VJ}=125^\circ\text{C}$ $t=10\text{ms}$ , sine	6000	A
$I^2t$	$T_{VJ}=125^\circ\text{C}$ $t=10\text{ms}$ , sine	180000	$\text{A}^2\text{s}$
$V_{isol}$	a.c.50HZ;r.m.s.;1min, $I_{iso}:2\text{mA}(\text{MAX})$	4000	V
$T_{vj}$		-40 to 125	$^\circ\text{C}$
$T_{stg}$		-40 to 125	$^\circ\text{C}$
$M_t$	To terminals(M8)	$12\pm 15\%$	Nm
$M_s$	To heatsink(M6)	$6\pm 15\%$	Nm
$di/dt$	$T_{VJ}=T_{VJM}$ , $V_{DM}\leq 2/3V_{DRM}$ , $I_{GM}=1.5\text{A}$ $t_r\leq 0.5\mu\text{s}$	100	$\text{A}/\mu\text{s}$
$dv/dt$	$T_{VJ}=T_{VJM}$ , $2/3V_{DRM}$ , linear voltage rise	1000	$\text{V}/\mu\text{s}$
Weight	Module(Approximately)	870	g

## Thermal Characteristics

Symbol	Conditions	Values	Units
$R_{th(j-c)}$	per chip	0.12	$^\circ\text{C}/\text{W}$
$R_{th(c-h)}$	per chip	0.04	$^\circ\text{C}/\text{W}$



Electrical Characteristics

Symbol	Conditions	Values			Units
		Min.	Typ.	Max.	
$V_{TM}$	$T=25^{\circ}C$ $I_{TM}=600A$			2.5	V
$I_{RRM}/I_{DRM}$	$T_{VJ}=T_{VJM}$ , $V=V_{RRM}$ , $V=V_{DRM}$			40	mA
$V_{TO}$	$T_{VJ}=T_{VJM}$			0.95	V
$r_T$	$T_{VJ}=T_{VJM}$			1.2	m $\Omega$
$V_{GT}$	$T_{VJ}=25^{\circ}C$ , $V_D=12V$ , $R_L=3\Omega$	0.8		2.5	V
$I_{GT}$	$T_{VJ}=25^{\circ}C$ , $V_D=12V$ , $R_L=3\Omega$	30		150	mA
$I_L$	$T_{VJ}=25^{\circ}C$ , $V_D=12V$ , $R_L=3\Omega$			1000	mA
$I_H$	$T_{VJ}=25^{\circ}C$ , $V_D=12V$ , $R_L=3\Omega$	20		150	mA
$V_{GD}$	$T_{VJ}=T_{VJM}$ , $V_{DM}=67\%V_{DRM}$	0.2			V

Performance Curves

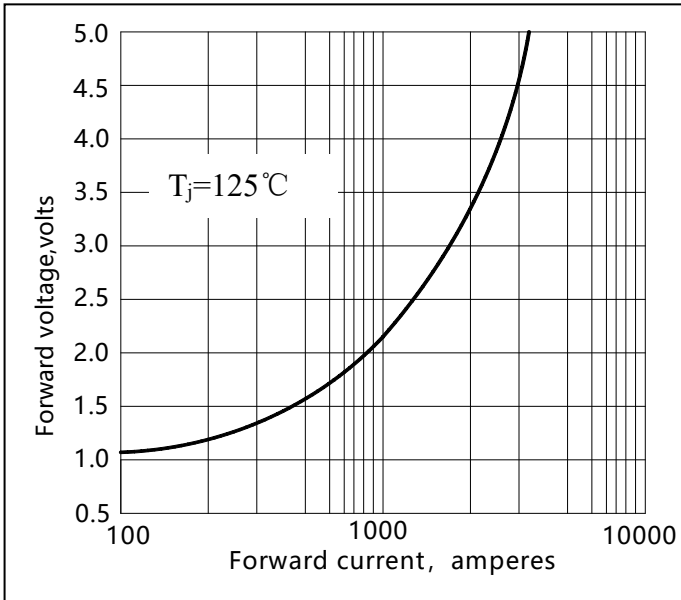


Fig1. Peak On-state Voltage Vs Peak On-state

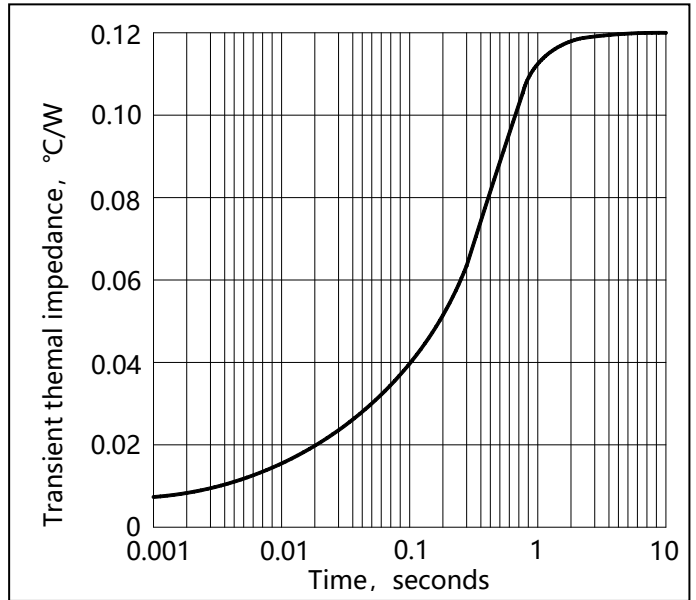


Fig2. Max. junction To case Thermal Impedance Vs Time

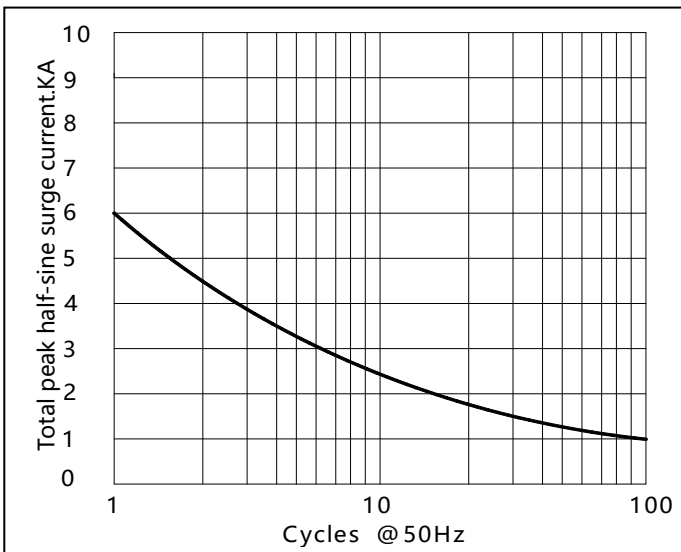


Fig3. Surge Current Vs Cycles

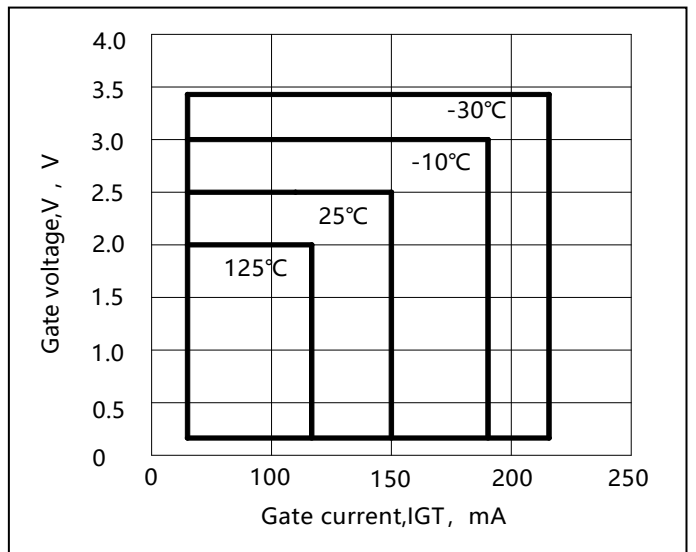


Fig4. Gate Trigger Zone Vs temperature

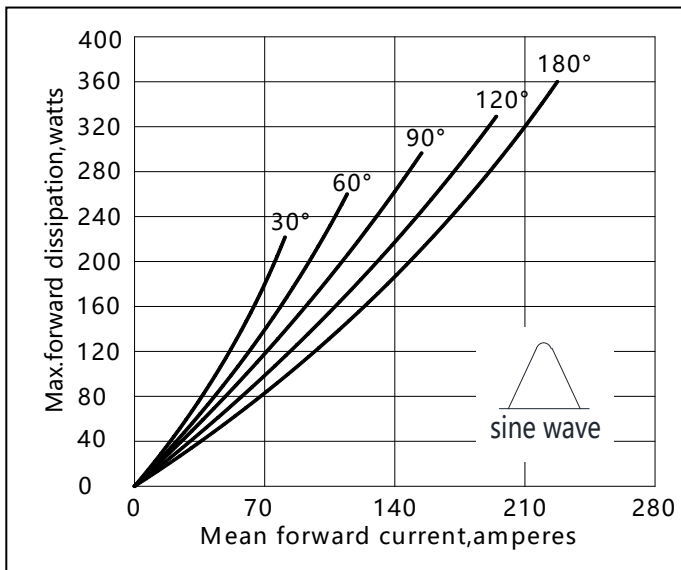


Fig5. Max. Power Dissipation Vs Mean On-state Current

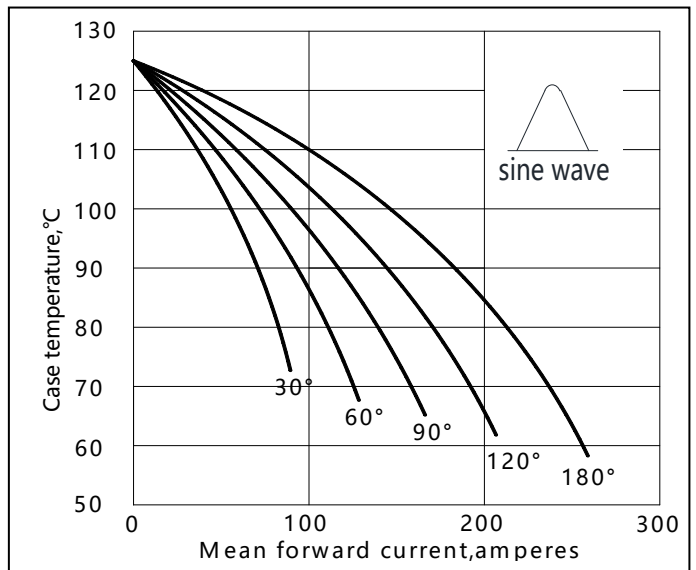
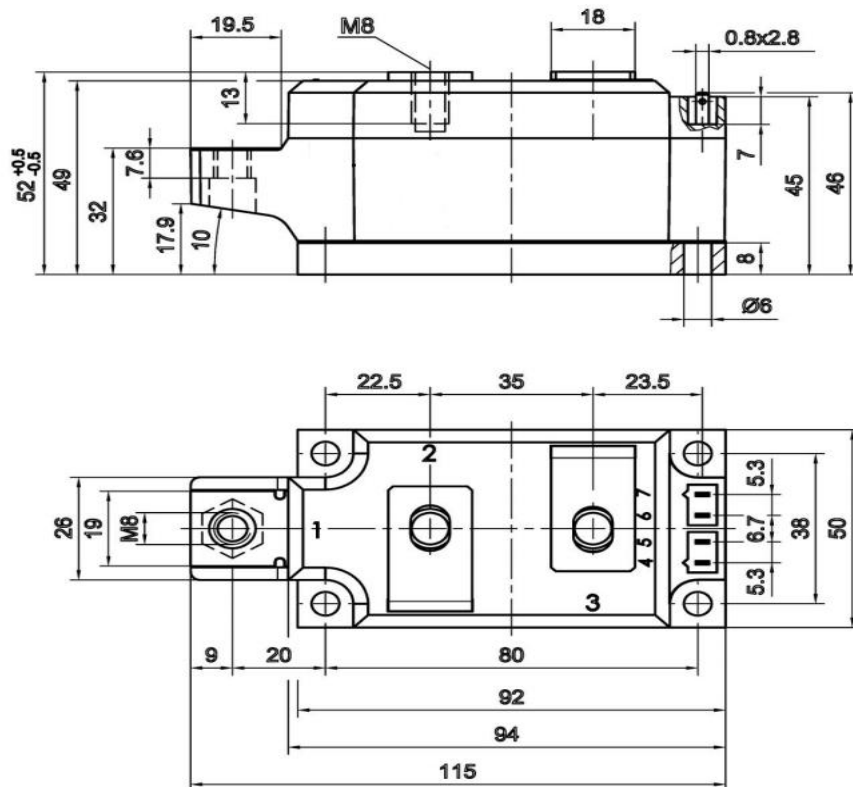


Fig6. Max case Temperature Vs Mean On-state Current

## Package Outline Information

### CASE:T3



Dimensions in mm

Unmarked dimensional tolerance: ±0.5mm